Product End-of-Life Disassembly Instructions

Product Category: Desktops	
Marketing Name / Model [List multiple models if applicable.]	
HP Elite SFF 805 G9 Desktop PC ENERGY STAR	Model Number: HSC-F006SF

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment.

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☐ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☒ Power supply PCB ☒ External Keyboard (KB) ☒ External Mouse ☒ Others: HDD PCB, Memory PCB	7
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☒ RTC/CMOS battery ☐ Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☐ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☐ Panel LCD	0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☒ Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexagon Screwdriver	T-15
Crisscross Screwdriver	PH1
Soldering Iron	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

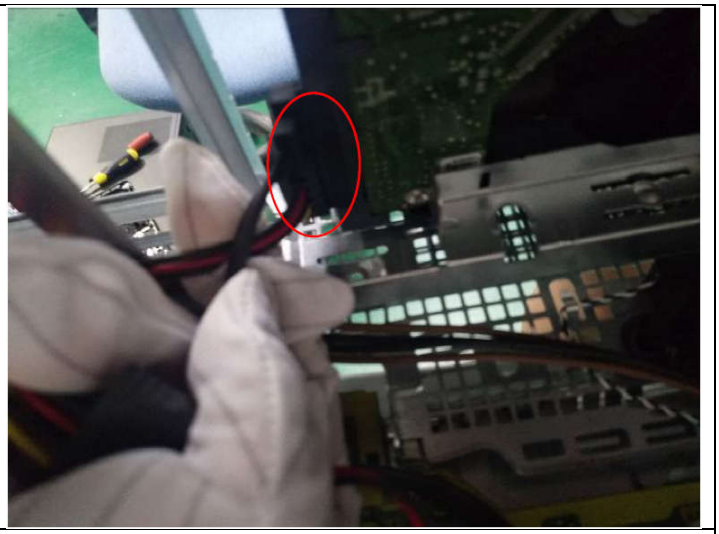
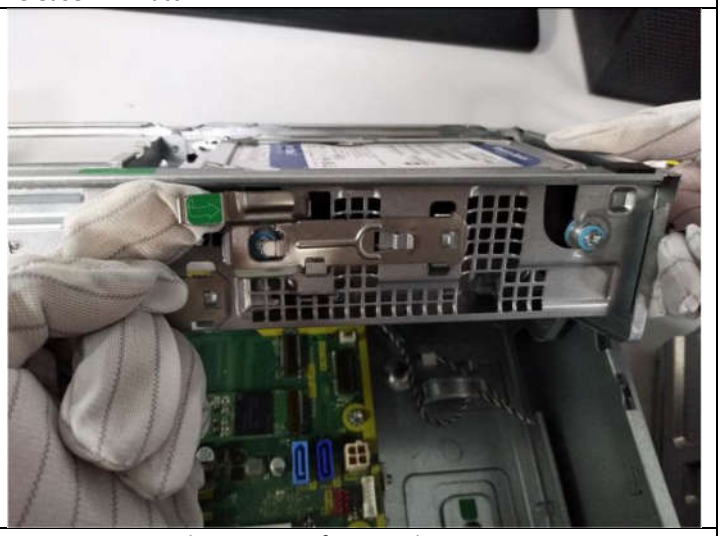
1. Use T-15 screwdriver to loose thumb screw and remove access panel.
2. Disconnect ODD power cable and ODD SATA cable from ODD.

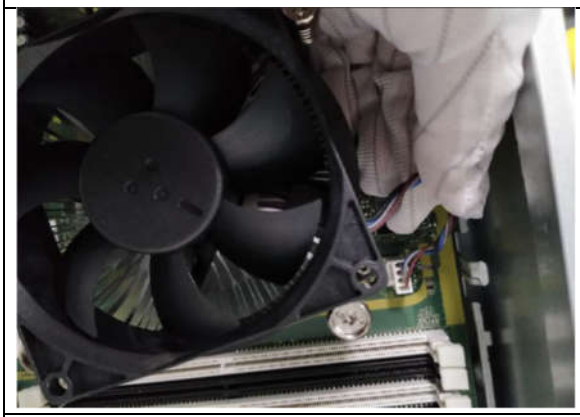
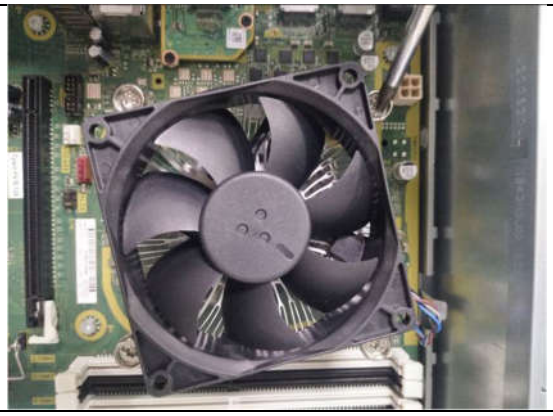
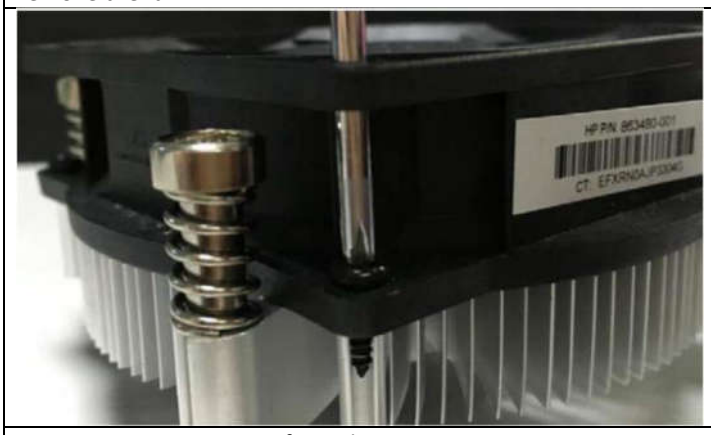
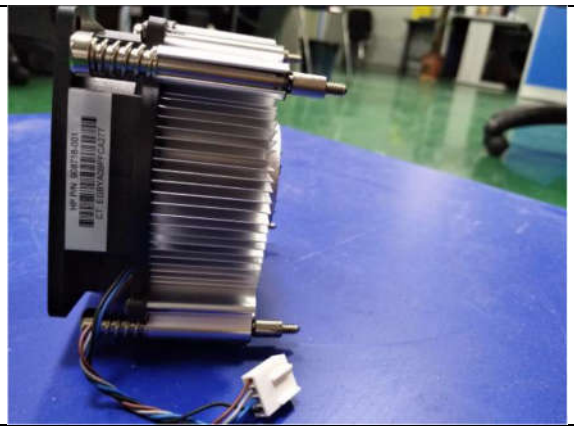
3. Press the ODD's latch on ODD cage
4. Remove the ODD from ODD cage
5. Remove Front Bezel from chassis
6. Disconnect HDD power cable and HDD SATA cable from HDD.
7. Remove the driver cage from Chassis
8. Use T-15 screwdriver to loose the screws of HDD and release HDD latch
9. Remove HDD from HDD cage
10. Remove the Fan duct from cooler
11. Disconnect Cooler Fan cable from MB
12. Use T-15 screw driver to loose the cooler screws and remove cooler from MB
13. Use T-15 screw driver to loose the screws and remove the fan
14. Separate the fan from CPU heat sink
15. Remove memory from the MB
16. Rotate the handle and open it up
17. Remove the CPU from the board
18. Remove SSD M.2 Card
19. Remove WLAN M.2 Card
20. Remove the battery from the system board
21. Use T-15 screw driver to loose the screws of MB from board
22. Remove MB from chassis
23. Remove speaker from Chassis
24. Use T-15 screw driver to loose the screws of PSU
25. Press the PSU's latch on chassis
26. Remove the PSU from chassis
27. Remove the screws covered
28. Remove PSU cover
29. Use PH1 screw driver to remove FG screw
30. Disconnect fan connector and inlet connector
31. Loose screws and remove PCB from case
32. Loose screws and remove PSU fan
33. Use Soldering to remove Ele-Cap from PCBA

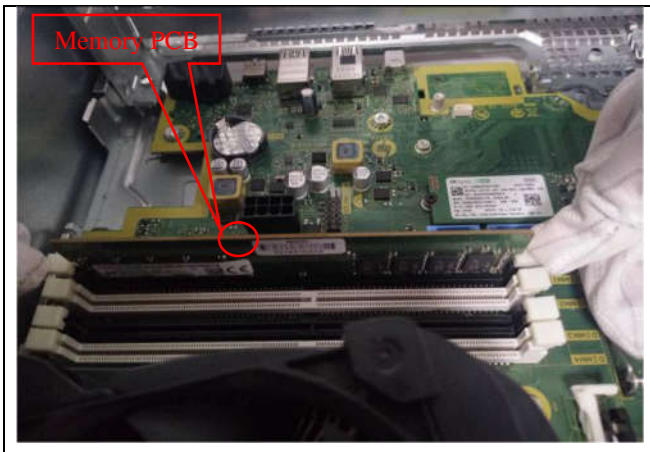
3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

Step1 Use T-15 screw driver to Loose thumb screw and remove access panel.	Step2 Disconnect ODD power cable and ODD SATA cable from ODD.

	
Step3 Press the ODD’s latch on ODD cage	Step4 Remove the ODD from ODD cage
	
Step5 Remove Front Bezel from chassis	Step6 Disconnect HDD power cable and HDD SATA cable from HDD.

	
Step7 Remove the driver cage from Chassis	Step8 Use T-15 screw driver to loose the screws of HDD and release HDD latch.
	
Step 9.Remove HDD from HDD cage	Step10 Remove the Fan Duct from cooler

	
Step11 Disconnect Cooler Fan cable from MB	Step12 Use T-15 screw driver to loose the cooler screws and remove cooler from MB
	
Step13 Use T-15 screwdriver to loose the screws and remove the fan	Step14 Separate the fan from CPU heat sink
	
Step15 Remove memory from the MB	Step16 Rotate the handle and open it up



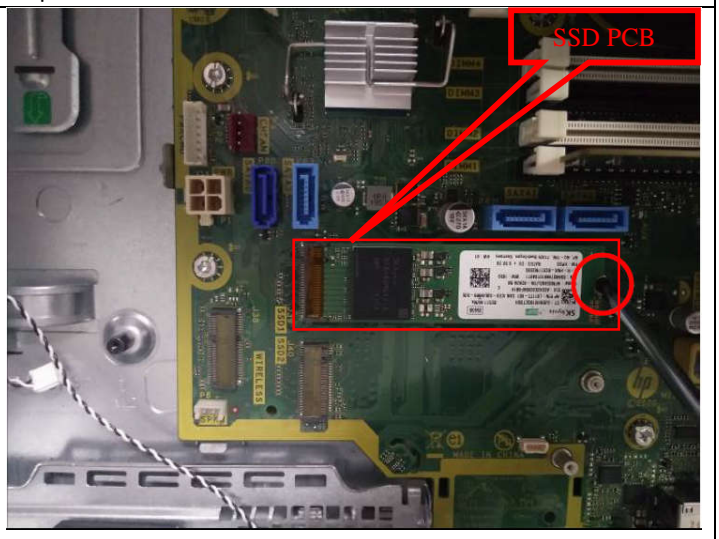
Step17 Remove the CPU from the board



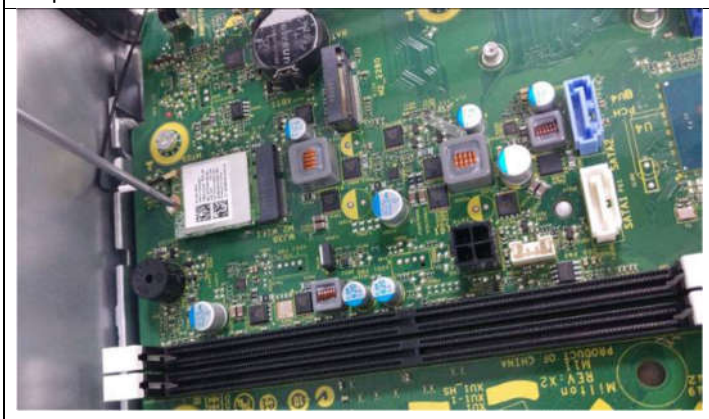
Step18 Remove SSD M.2 Card



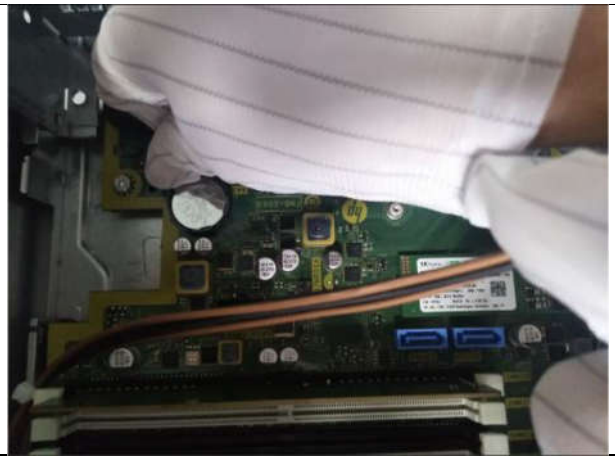
Step19 Remove WLAN M.2 Card



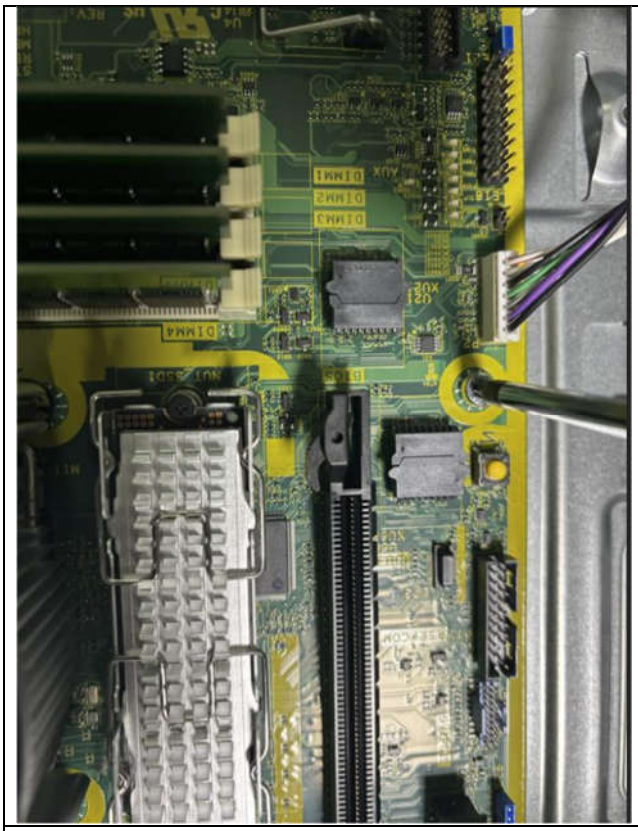
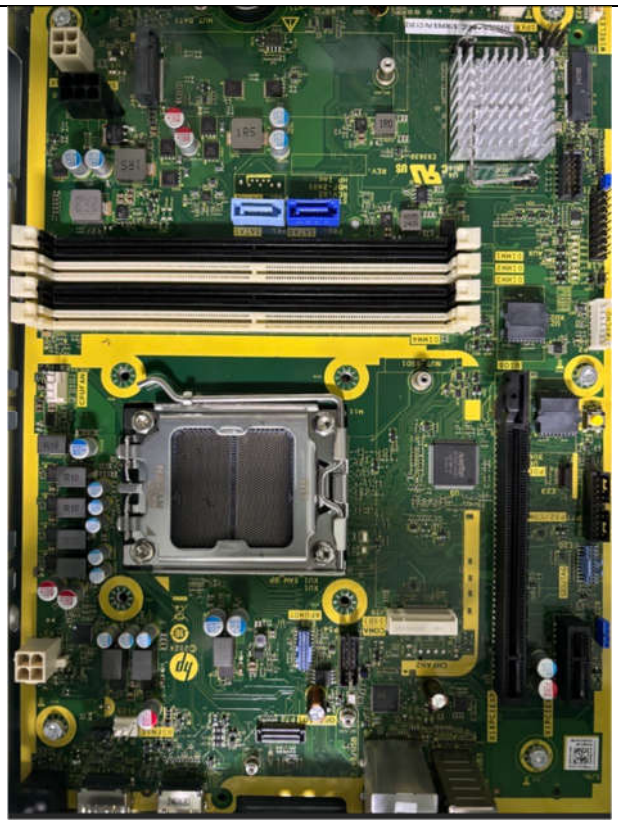
Step20 Remove the battery from the system board



Step21 Use T-15 screwdriver to loose the screws of MB from board



Step22 Remove MB from chassis

	
Step23 Remove speaker from Chassis	Step24 Use T-15 screwdriver to loose the screws of PSU
	
Step25 Press the PSU’s latch on chassis	Step26 Remove the PSU from chassis



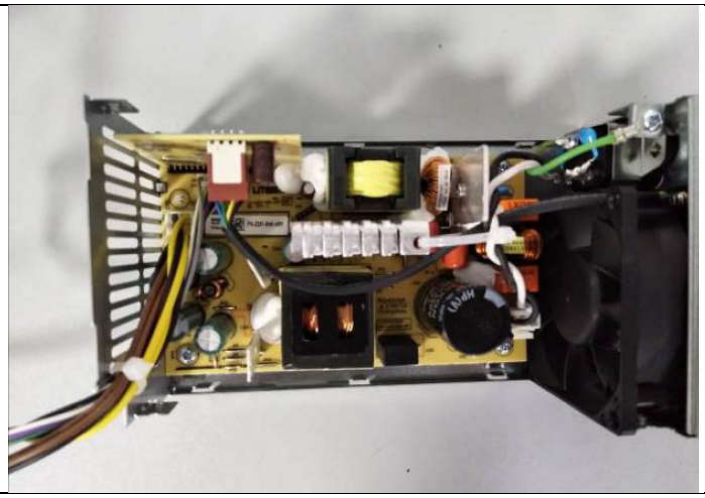
Step27 Remove screws covered



Step28 Remove PSU cover



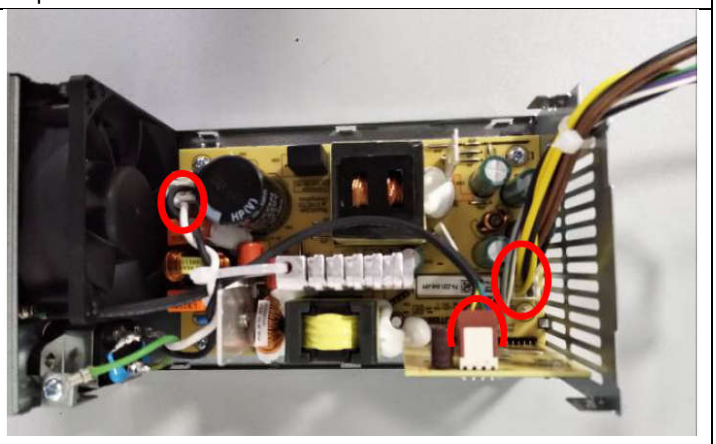
Step29 Use PH1 screw driver to remove FG screw



Step30 Disconnect fan connector and inlet connector

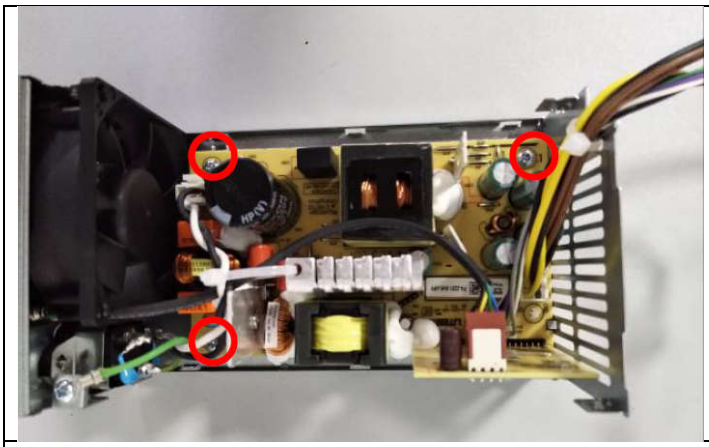
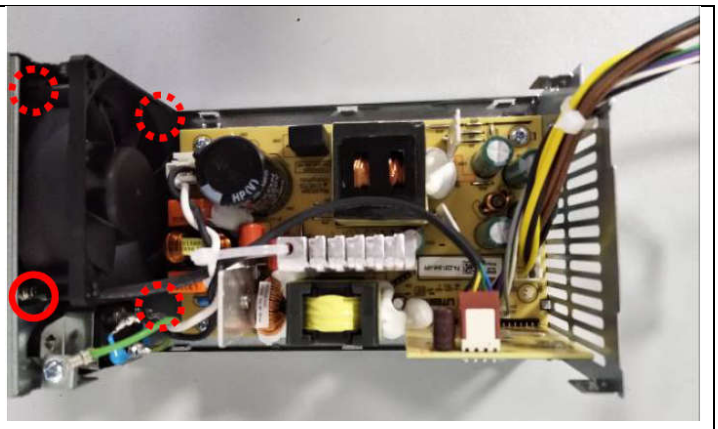


Step31 Loose screws and remove PCB from case



Step32 Loose screws and remove PSU fan

HP Inc. instructions for this template are available at EL-MF877-01

	
Step33 Heat the solder of the Ele-Cap and Remove it from PCBA	
